ABSTRACT OF THE DISCLOSURE

Disclosed is a semiconductor device constructed such that a lead wire extending from an interposer is connected to a pad of a chip, wherein the chip is bonded to a resin molding with a high mechanical strength. In the semiconductor device of the present invention, the lead wires extending from the interposer formed of a polyimide film are connected to the pad of the chip, and the lead wires are arranged sparse. Dummy lead wires irrelevant to the electrical connection are also arranged in addition to the lead wires extending from the interposer so as to increase the total number of lead wires supporting the chip so as to permit the chip 11 to be bonded to the resin molding 15 with a high mechanical strength. The dummy lead wires mounted to the interposer together with the lead wires serve to improve the bonding strength between the resin molding and the chip.